SDAS142C – JULY 1987 – REVISED AUGUST 1995

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- pnp Inputs Reduce dc Loading
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. With the 'ALS240A, 'ALS241C, 'AS240A, and 'AS241A, these devices provide the choice of selected combinations of inverting outputs, symmetrical active-low output-enable (\overline{OE}) inputs, and complementary OE and \overline{OE} inputs.

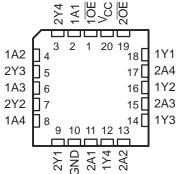
The -1 version of SN74ALS244C is identical to the standard version, except that the recommended maximum I_{OL} for the -1 version is 48 mA. There is no -1 version of the SN54ALS244C.

The SN54ALS244C and SN54AS244A are characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ALS244C and SN74AS244A are characterized for operation from 0°C to 70°C.

SN54ALS244C, SN54AS244A J PACKAGE
SN74ALS244C, SN74AS244A DW OR N PACKAGE
(TOP VIEW)

SN54ALS244C, SN54AS244A . . . FK PACKAGE

(TOP VIEW)



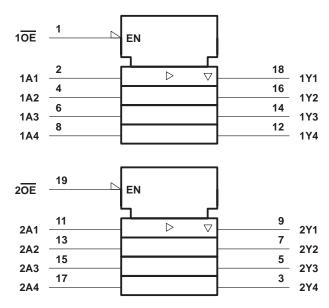
FUNCTION TABLE
(each buffer)

INPU	JTS	OUTPUT
OE	Α	Y
L	Н	Н
L	L	L
н	Х	Z

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

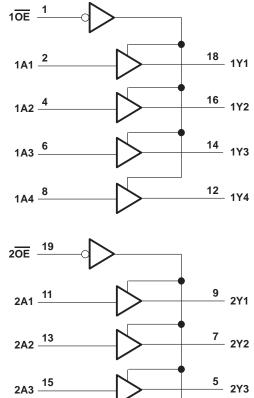
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



2A3 _____ 2Y3 _____ 2Y3 _____ 2Y3 _____ 2Y4

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	
Input voltage, V ₁	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN54ALS244C	-55°C to 125°C
SN74ALS244C	0°C to 70°C
Storage temperature range	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



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recommended operating conditions

		SN54ALS244C		4C	SN7	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V				0.8†			0.8	V
VIL	Low-level input voltage			0.7‡				v
IOH	High-level output current			-12			-15	mA
	l ou lovel output ourrest			12			24	mA
IOL	Low-level output current						48§	ША
Т _А	Operating free-air temperature	-55		125	0		70	°C

[†] Applies over temperature range –55°C to 70°C

[‡]Applies over temperature range 70°C to 125°C

§ Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEOT	CONDITIONS	SN	SN54ALS244C		SN7	4ALS24	4C	
PARAMETER	IESTO	TEST CONDITIONS		TYP¶	MAX	MIN	TYP¶	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lı = –18 mA			-1.5			-1.5	V
	V _{CC} = 4.5 V to 5.5 V	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		
Vari	VCC = 4.5 V 10 5.5 V	$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
VOH		I _{OH} = -12 mA	2						v
	$V_{CC} = 4.5 V$	I _{OH} = -15 mA				2			
		I _{OL} = 12 mA		0.25	0.4		0.25	0.4	
VOL	$V_{CC} = 4.5 V$	I _{OL} = 24 mA					0.35	0.5	V
		I _{OL} = 48 mA (-1 version)					0.35	0.5	
lozh	V _{CC} = 5.5 V,	$V_{O} = 2.7 V$			20			20	μΑ
IOZL	V _{CC} = 5.5 V,	$V_{O} = 0.4 V$			-20			-20	μΑ
l	V _{CC} = 5.5 V,	$V_{I} = 7 V$			0.1			0.1	mA
ЧΗ	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
۱ _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
IO#	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
		Outputs high		9	18		9	17	
ICC	V _{CC} = 5.5 V	Outputs low		15	25		15	24	mA
		Outputs disabled		17	29		17	27	

¶ All typical values are at V_{CC} = 5 V, T_A = 25°C. [#] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.



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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL R1 R2	C = 4.5 = 50 pF = 500 Ω = 500 Ω = 500 Ω	3	UNIT	
				S244C	SN74AL		
			MIN	MAX	MIN	MAX	
^t PLH	A	v	1	16	2	10	ns
^t PHL		Ŷ	3	12	3	10	115
^t PZH		Y	1	26	3	20	ns
tPZL	OE	Y	1	24	3	20	115
^t PHZ	OE	V	2	10	2	10	ns
^t PLZ	UE	T T	1	26	1	13	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	
Input voltage, V ₁	
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T _A : SN54AS244A	-55°C to 125°C
SN74AS244A	0°C to 70°C
Storage temperature range	-65°C to 150°C

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54AS244A		SN	UNIT			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
IOH	High-level output current			-12			-15	mA
IOL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C



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DADAMETED	TEST O	TEST CONDITIONS			SN54AS244A		74AS244	4A	UNIT
PARAMETER	TESTO	UNDITIONS	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lj = -18 mA			-1.2			-1.2	V
	V_{CC} = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		
Ver		I _{OH} = -3 mA	2.4	3.4		2.4	3.4		V
VOH	$V_{CC} = 4.5 V$	$I_{OH} = -12 \text{ mA}$	2.4						v
		I _{OH} = -15 mA				2.4			
Mar		I _{OL} = 48 mA			0.55				V
VOL	$V_{CC} = 4.5 V$	I _{OL} = 64 mA						0.55 V	
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μΑ
IOZL	V _{CC} = 5.5 V,	V _O = 0.4 V			-50			-50	μΑ
l	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
IIH	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μA
OE					-0.5			-0.5	
IIL A	$V_{CC} = 5.5 V,$	$V_{I} = 0.4 V$			-1			-1	mA
10 [‡]	V _{CC} = 5.5 V,	V _O = 2.25 V	-50		-150	-50		-150	mA
ICC		Outputs high		22	34		22	34	
	V _{CC} = 5.5 V	Outputs low		60	90		60	90	mA
		Outputs disabled		34	54		34	54	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
 ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

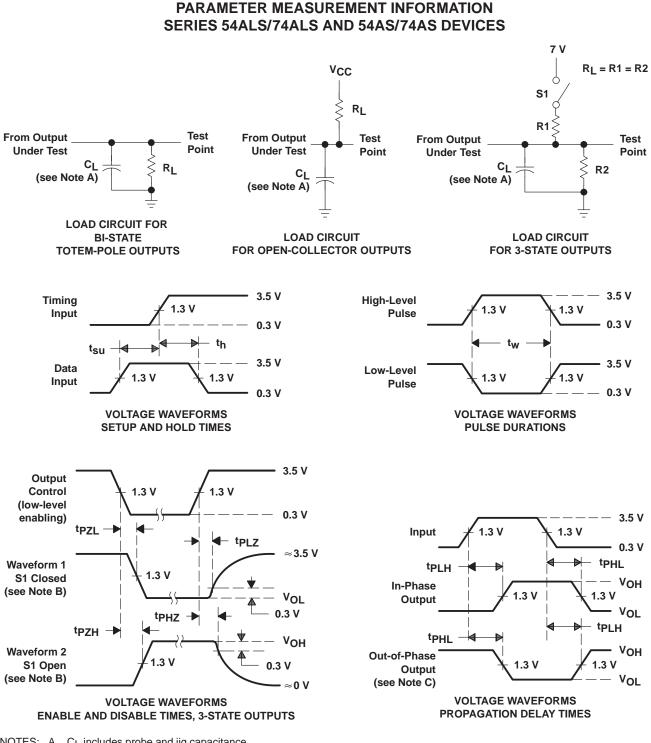
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C R R	5 V, §	UNIT		
			SN54AS244A SN74AS244A			S244A	
			MIN	MAX	MIN	MAX	
^t PLH		N N	2	9	2	6.2	
^t PHL	A	Y	1	7	1	6.2	ns
^t PZH		N N	1	10	1	9	ns
^t PZL	ŌĒ	Y	2	8	2	7.5	115
^t PHZ	OE	Y	1	6.5	1	6	ns
^t PLZ	UE		1	10.5	1	9	115

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control. C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: $PRR \le 1$ MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-86839012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 86839012A SNJ54ALS 244CFK	Samples
5962-8683901RA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8683901RA SNJ54ALS244CJ	Samples
5962-8683901SA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8683901SA SNJ54ALS244CW	Samples
5962-8683901VRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8683901VR A SNV54ALS244CJ	Samples
5962-8683901VSA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8683901VS A SNV54ALS244CW	Samples
5962-9755901QRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9755901QR A SNJ54AS244AJ	Samples
JM38510/38303B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type		JM38510/ 38303B2A	Samples
JM38510/38303BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type		JM38510/ 38303BRA	Samples
M38510/38303B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 38303B2A	Samples
M38510/38303BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 38303BRA	Samples
SN54ALS244CJ	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54ALS244CJ	Samples
SN54AS244AJ	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54AS244AJ	Samples
SN74ALS244C-1DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C-1	Samples
SN74ALS244C-1N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS244C-1N	Samples
SN74ALS244C-1NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C-1	Samples



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS244CDBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	G244C	Samples
SN74ALS244CDWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C	Samples
SN74ALS244CN	ACTIVE	PDIP	Ν	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS244CN	Samples
SN74ALS244CNSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C	Samples
SN74AS244ADWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS244A	Samples
SN74AS244AN	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74AS244AN	Samples
SN74AS244ANE4	ACTIVE	PDIP	Ν	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74AS244AN	Samples
SN74AS244ANSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS244A	Samples
SNJ54ALS244CFK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 86839012A SNJ54ALS 244CFK	Samples
SNJ54ALS244CJ	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8683901RA SNJ54ALS244CJ	Samples
SNJ54ALS244CW	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8683901SA SNJ54ALS244CW	Samples
SNJ54AS244AJ	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9755901QR A SNJ54AS244AJ	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.



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PACKAGE OPTION ADDENDUM

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS244C, SN54ALS244C-SP, SN54AS244A, SN74ALS244C, SN74AS244A :

- Catalog : SN74ALS244C, SN54ALS244C, SN74AS244A
- Military : SN54ALS244C, SN54AS244A
- Space : SN54ALS244C-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application



Texas

STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS244C-1DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS244C-1NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74ALS244CDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ALS244CDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS244CNSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74AS244ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74AS244ANSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1



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PACKAGE MATERIALS INFORMATION

16-Apr-2024



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS244C-1DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS244C-1NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS244CDBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74ALS244CDWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS244CNSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AS244ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AS244ANSR	SO	NS	20	2000	367.0	367.0	45.0

TEXAS INSTRUMENTS

*All dimensions are nominal

SN74AS244ANE4

SNJ54ALS244CFK

SNJ54ALS244CW

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W (mm)

12.06

26.16

26.16

12.06

12.06

13.97

13.97 13.97

13.97

12.06

26.16

T (µm)

2030

6220

6220

2030

2030

11230

11230

11230

11230

2030

6220

B (mm)

NA

NA

NA

NA

NA

4.32

4.32

4.32

4.32

NA

NA

16-Apr-2024

TUBE



20

20

20

20

55

25

506

506.98

506.98

- B - Alignment groove width

Γ	Device	Package Name	Package Type	Pins	SPQ	L (mm)
	5962-86839012A	FK	LCCC	20	55	506.98
	5962-8683901SA	W	CFP	20	25	506.98
Γ	5962-8683901VSA	W	CFP	20	25	506.98
Γ	JM38510/38303B2A	FK	LCCC	20	55	506.98
Γ	M38510/38303B2A	FK	LCCC	20	55	506.98
Γ	SN74ALS244C-1N	N	PDIP	20	20	506
Γ	SN74ALS244CN	N	PDIP	20	20	506
Γ	SN74AS244AN	N	PDIP	20	20	506

PDIP

LCCC

CFP

Ν

FK

W

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice. В.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only.
 E. Falls within Mil-Std 1835 GDFP2-F20



DB0020A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-150.



DB0020A

EXAMPLE BOARD LAYOUT

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DB0020A

EXAMPLE STENCIL DESIGN

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK 20

8.89 x 8.89, 1.27 mm pitch

GENERIC PACKAGE VIEW

LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



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EXAMPLE BOARD LAYOUT

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DW0020A

EXAMPLE STENCIL DESIGN

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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